



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Garnik Taheri  
SERIAL NO.: 10/754,807  
FILING DATE: January 8, 2004 CONFIRMATION NO.: 1589  
TITLE: SINGLE IC PACKAGING SOLUTION FOR MULTI CHIP  
MODULES  
EXAMINER: Roy Karl Potter  
ART UNIT: 2822

**CERTIFICATE OF MAILING**

I hereby certify that this paper is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450, on the date printed below:

Date: 11/16/05

Name: Michelle R. Crosby

Michelle R. Crosby

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

Dear Sir:

This paper is responsive to the Office Action mailed **August 10, 2005**. Please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims, which begins on page 4 of this paper.

**Remarks** begin on page 8 of this paper.